Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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MAZTxxxH Series

Silicon planar type

For surge absorption circuit

■ Features

- Two elements anode-common type
- Power dissipation P_D : 150 mW

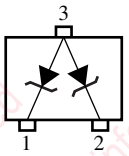
■ Package

- Pin Name
  SSMini3-F2
- Pin Name
  1: Cathode 1
  2: Cathode 2
  3: Anode

■ Marking Symbol

Refer to the list of the electrical characteristics within part numbers

■ Internal Connection



■ Absolute Maximum Ratings $T_a = 25°C$

Parameter	Symbol	Rating	Unit
Power dissipation *	P_D	150	mW
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	−55 to +150	°C

Note) *: P_D = 150 mW achieved with a printed circuit board.

■ Common Electrical Characteristics $T_a = 25°C \pm 3°C$

Parameter	Symbol	Conditions		Min	Typ	Max	Unit
Zener voltage*	V_Z	I_Z	Specified value	Refer to the list of the electrical characteristics within part numbers			V
Zener rise operating resistance	R_{ZK}	I_Z	Specified value				Ω
Zener operating resistance	R_Z	I_Z	Specified value				Ω
Reverse current	I_R	V_R	Specified value				μA

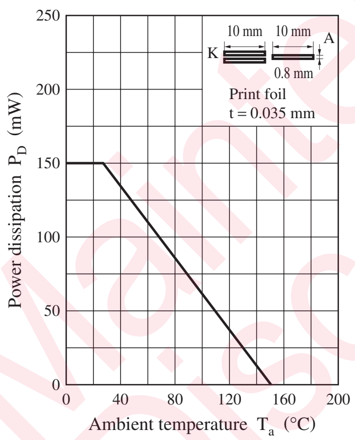
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. Electrostatic breakdown voltage: ±10 kV
Test method: IEC1000-4-2 (C = 150 pF, R = 330 Ω, Contact discharge: 10 times)
3. *: The temperature must be controlled 25°C for V_Z mesurement.
V_Z value measured at other temperature must be adjusted to V_Z (25°C)
V_Z guaranted 20 ms after current flow.

■ Electrical characteristics within part numbers $T_a = 25°C \pm 3°C$

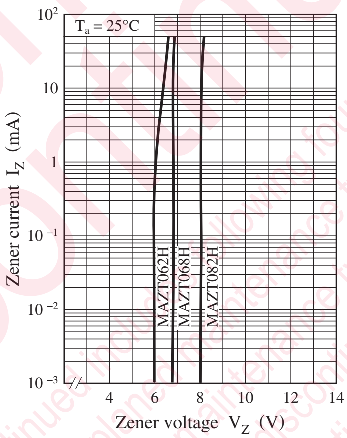
Part number	Zener voltage V_Z (V)				Reverse current I_R (mA)		Zener operating resistance R_Z (Ω)	Zener rise operating resistance R_{ZK} (Ω)	Marking symbol
	Min	Nom	Max	I_Z (mA)	Max	V_R (V)	I_Z = 5 mA Max	I_Z = 0.5 mA Max	
MAZT062H	5.8	6.2	6.6	5	0.2	4	50	100	6.2Z
MAZT068H	6.4	6.8	7.2	5	0.1	4	30	60	6.8Z
MAZT082H	7.7	8.2	8.7	5	0.1	5	30	60	8.2Z

Note) ∗: I_Z = 1.0 mA

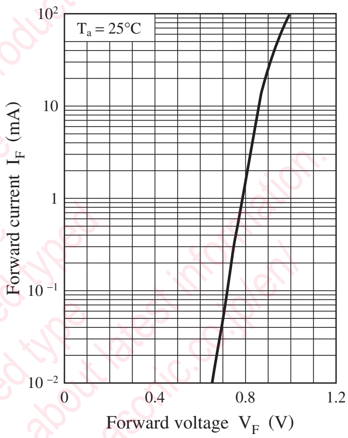
P_D — T_a



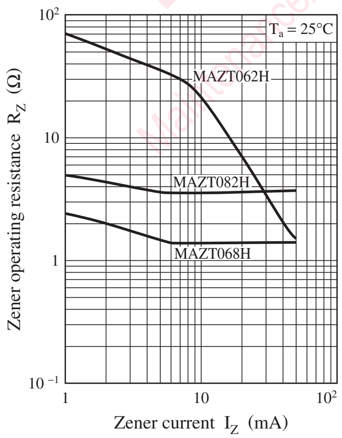
I_Z — V_Z



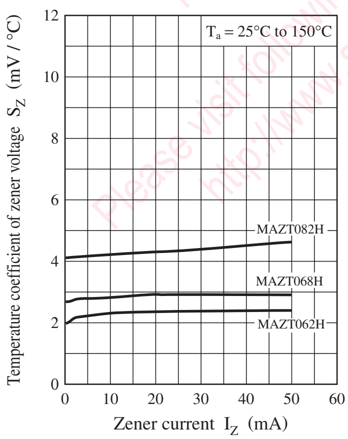
I_F — V_F



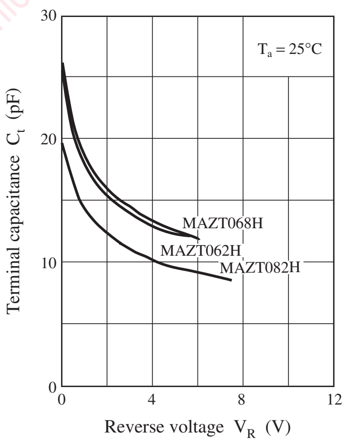
R_Z — I_Z



S_Z — I_Z

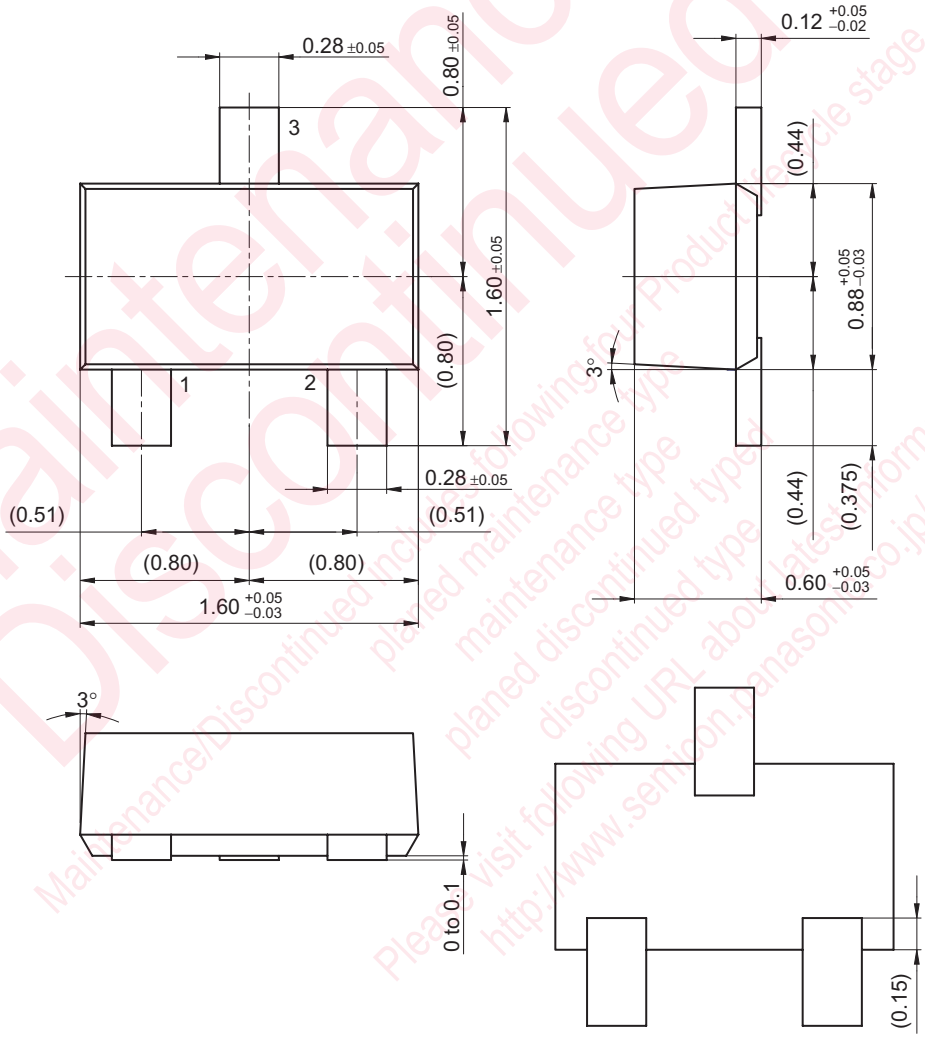


C_t — V_R



SSMini3-F2

Unit: mm



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(6) Comply with the instructions for use in order to prevent breakdown and characteristics change due to external factors (ESD, EOS, thermal stress and mechanical stress) at the time of handling, mounting or at customer's process. When using products for which damp-proof packing is required, satisfy the conditions, such as shelf life and the elapsed time since first opening the packages.